

MA2S728

Silicon epitaxial planar type

For switching

■ Features

- High-density mounting is possible
- Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

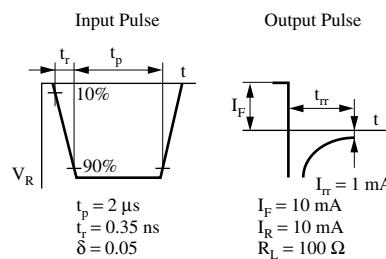
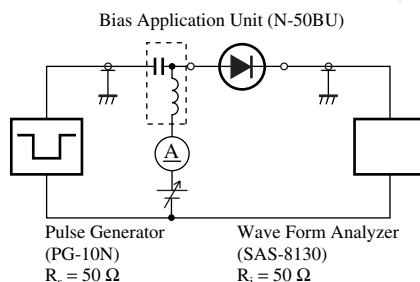
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Peak forward current	I_{FM}	150	mA
Forward current	I_F	30	mA
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

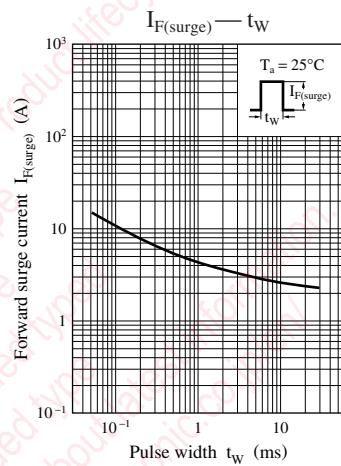
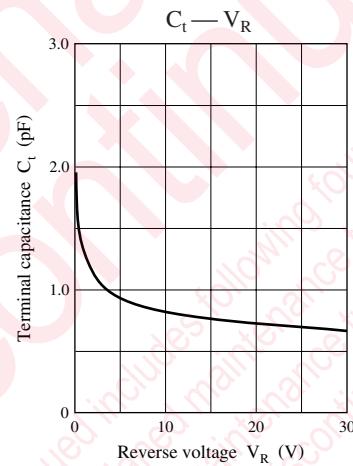
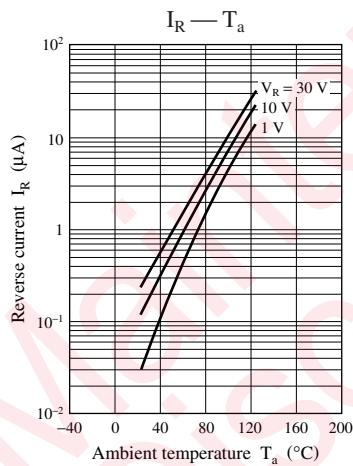
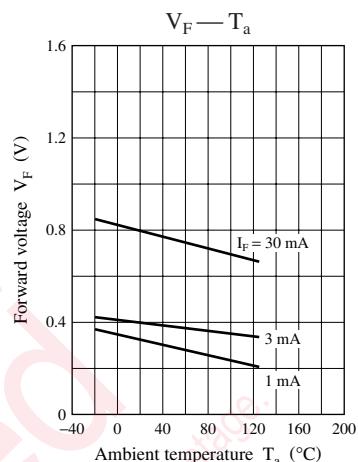
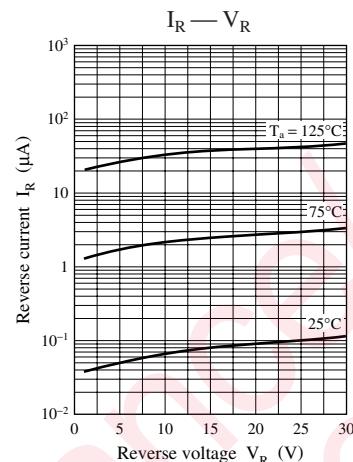
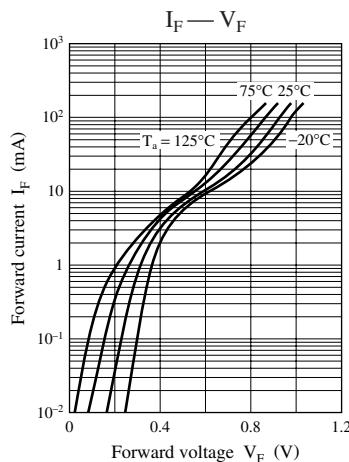
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	C_t	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$			1.5	pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 10 \text{ mA}$ $I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$			1.0	ns
Detection efficiency	η	$V_{IN} = 3 \text{ V}_{(\text{peak})}, f = 30 \text{ MHz}$ $R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$			65	%

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz.
4. *: t_{rr} measurement circuit





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